

## **TO-220AB Plastic-Encapsulate MOSFETS**

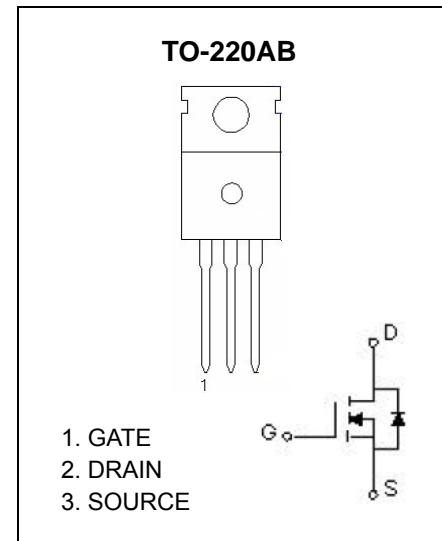
### **IRF630 N-Channel Power MOSFET**

#### **GENERAL DESCRIPTION**

It uses advanced trench technology and design to provide excellent  $R_{DS(on)}$  with low gate charge .This device is suitable for high current load applications.

#### **FEATURE**

- High current rating
- Ultra lower  $R_{DS(on)}$
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation



#### **APPLICATION**

- Power switching application
- Load switching in high circuit application
- DC/DC converters

#### **Maximum ratings ( $T_a=25^\circ\text{C}$ unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	200	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$I_D$	9.3	A
Pulsed Drain Current	$I_{DM}$	37	
Single Pulsed Avalanche Energy (note1)	$E_{AS}$	250	mJ
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 ~+150	
Maximum lead temperature for soldering purposes , 1/8"from case for 5 seconds	$T_L$	260	

## Electrical characteristics ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Off characteristics</b>						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	200			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 200V, V_{GS} = 0V$			25	$\mu\text{A}$
Gate-body leakage current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$			$\pm 100$	nA
<b>On characteristics (note2)</b>						
Gate-threshold voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2		4	V
Static drain-source on-resistance	$R_{DS(\text{on})}$	$V_{GS} = 10V, I_D = 5.4\text{A}$			400	$\text{m}\Omega$
Forward transconductance	$g_{fs}$	$V_{DS} = 50V, I_D = 5.4\text{A}$	3.8			S
<b>Dynamic characteristics (note 3)</b>						
Input capacitance	$C_{iss}$	$V_{DS} = 25V, V_{GS} = 0V, f = 1\text{MHz}$		800		pF
Output capacitance	$C_{oss}$			240		
Reverse transfer capacitance	$C_{rss}$			76		
<b>Switching characteristics (note 3)</b>						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 100V, V_{GS} = 10V, R_G = 12\Omega, I_D = 5.9\text{A}$		9.4		ns
Turn-on rise time	$t_r$			28		
Turn-off delay time	$t_{d(off)}$			39		
Turn-off fall time	$t_f$			20		
<b>Drain-Source Diode Characteristics</b>						
Drain-source diode forward voltage(note2)	$V_{SD}$	$V_{GS} = 0V, I_S = 9\text{A}$			2	V
Continuous drain-source diode forward current(note4)	$I_S$				9.3	A
Pulsed drain-source diode forward current	$I_{SM}$				37	A

### Notes :

1.  $L = 4.6\text{mH}, I_L = 9.9\text{A}, V_{DD} = 50V, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$ .
2. Pulse Test : Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Guaranteed by design, not subject to production
4. Surface mounted on FR4 board,  $t \leq 10\text{s}$